



Docket No.: M4065.0226/P226  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Tongbi Jiang

Application No.: 09/484,437

Confirmation No.: 9698

Filed: January 18, 2000

Art Unit: 2813

For: Die attach curing method for semiconductor  
device

Examiner: J. M. Mitchell

**AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. 1.116**

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated January 11, 2006 (Part of Paper No. 122005), finally rejecting claims 1-3, 5-9, 11, 12, 14, 16-20 and 33-50, please consider the following Remarks.

*Do not  
enter  
6/26/06*